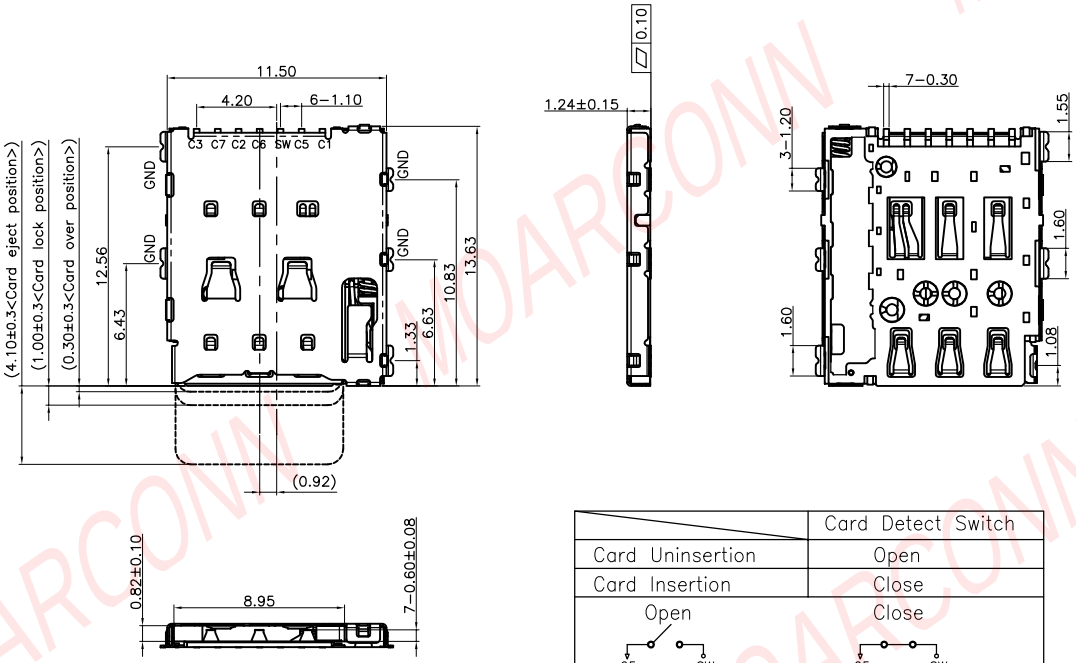
All materials,plating and process meet HF requirements.

Notes:
1.Material:
Housing: High Temperature Thermoplastic
Terminal:Copper Alloy
Shell: Stainless Steel
2.Plating:
Terminal:50u" Ni Underplated Overall
1u" Plated On Contact Area
G/F Plated On Solder Area
Sheel:30u" Ni Underplated Overall
G/F Plated On Contact Area And Solder Area
3.Technical Speciality:
Rated Voltage: 30V
Current Rating: 0.5A
Insulation Resistance:1000MΩ Min.
Contact Resistance:100mΩ Max.
Withstanding Voltage: 500V DC For 1 Minutes.
Operating Temperature:-40 ~+75℃ Humidity 80% R.H Max.



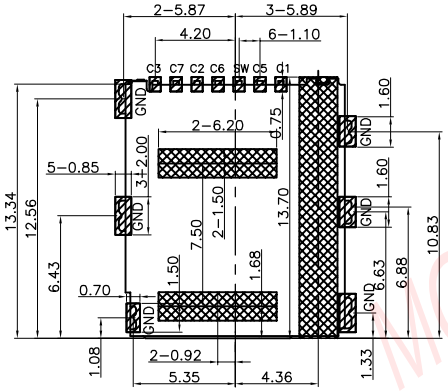
	Card Detect Switch
Card Uninsertion	Open
Card Insertion	Close
Open / Close	Close



PIN/NO	ASSIGNMENT
C1	Vcc
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	Detect Switch

SMT SOLDER AREA

COPPER RESTRICTED AREA
1.TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
2.NO FIRST PCB_LAYOUT CIRCUITS IN THE AREA



RECOMMENDED PCB LAYOUT

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	----	NEW RELEASE	Shilikai	2025.02.25

MOARCONN® More Connections Smart Future

DONG GUAN MOARCONN ELECTRONIC Co.,Ltd.

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

PRODUCT NAME : Nano SIM H1.24 Push-Push SMT	DRAWING: Shilikai	DATE: 2025.02.25	
PRODUCT NO. : NS124-T1150-30	CHECK: /	DATE: /	
DRAWING NO. : D-NS124-T1150-30	APPROVED: Aaron	DATE: 2025.06.03	
	SCALE: 1:1	DWG ID: C D	REV.: X0 / PAGE: 1 OF 1

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